

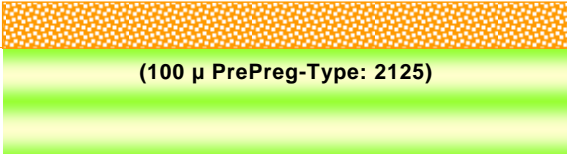



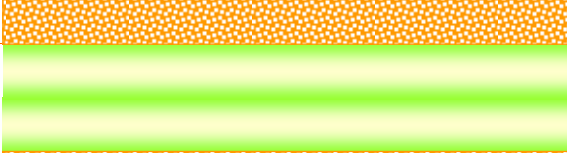
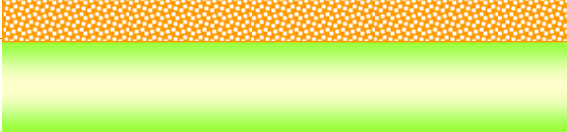
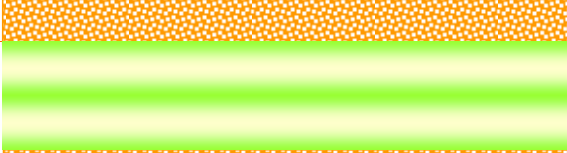

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper	 (100 μ PrePreg-Type: 2125)	A1
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-2	35 μ	Copper		A2
	200 μ	L-FR4		
	100 μ	Prepreg		
Layer-3	35 μ	Copper		A3
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-4	35 μ	Copper		A2
	200 μ	L-FR4		
	100 μ	Prepreg		
Layer-5	35 μ	Copper		A3
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-6	35 μ	Copper		A3
	200 μ	L-FR4		
	100 μ	Prepreg		
Layer-7	35 μ	Copper		A3
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-99	35 μ	Copper		

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